N-Channel 200 V (D-S) MOSFET

PRODUCT	PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)		
200	0.270 at V _{GS} = 10 V	10		

FEATURES

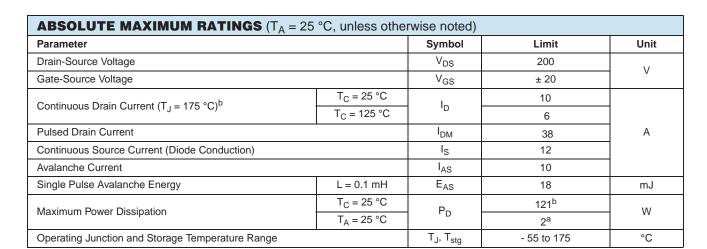
- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

G

Primary Side Switch

N-Channel MOSFET



THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
hunstion to Ambienta	$t \le 10 \text{ s}$	R _{thJA}	15	18	°C/W
Junction-to-Ambient ^a	Steady State		40	50	
Junction-to-Case (Drain)		R _{thJC}	0.85	1.1	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

G D S Top View

TO-220AB

RoHS





IRF630P



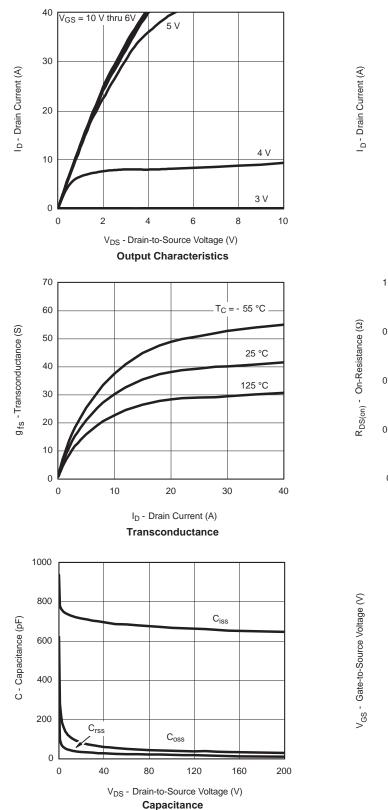
SPECIFICATIONS ($T_J = 25 \text{ °C}$, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	200		V		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V			1		
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			50	μA	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		0.270			
	R _{DS(on)}	V _{GS} = 10 V, I _D = 5 A, T _J = 125 °C		0.320		Ω	
Drain-Source On-State Resistance ^b		V _{GS} = 10 V, I _D = 5 A, T _J = 175 °C		0.410			
		V_{GS} = 4.5 V, I _D = 5 A		0.310			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 19 A		35		S	
Dynamic ^a	•						
Input Capacitance	C _{iss}			800		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		110			
Reverse Transfer Capacitance	C _{rss}			80			
Total Gate Charge ^c	Qg			30			
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 19 \text{ A}$		8		nC	
Gate-Drain Charge ^c	Q _{gd}			12			
Gate Resistance	Rg		0.5		2.9	Ω	
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	V_{DD} = 100 V, R _L = 5.2 Ω		50	75		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 19$ A, $V_{GEN} = 10$ V, $R_g = 2.5 \Omega$		30	45	ns	
Fall Time ^c	t _f			60	90		
Source-Drain Diode Ratings and Char	acteristics (Γ _C = 25 °C)					
Pulsed Current	I _{SM}				40	А	
Diode Forward Voltage ^b	V _{SD}	$I_{F} = 19 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 19 A, dl/dt = 100 A/μs		180	250	ns	

Notes:

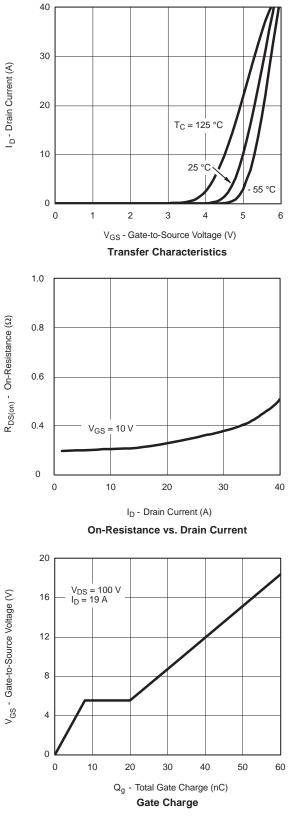
a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

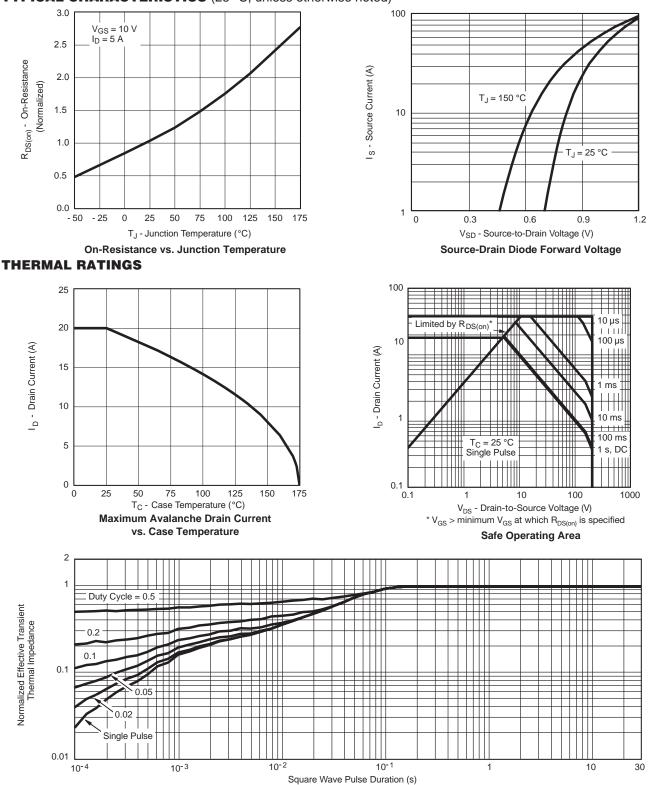




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





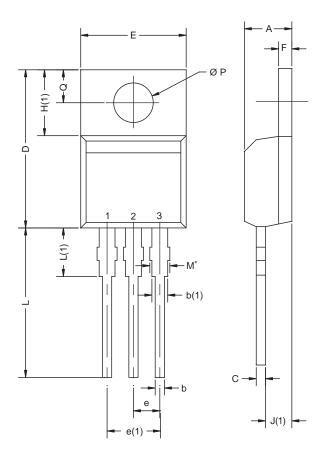


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Case



TO-220AB



	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0 DWG: 5471	0208-Rev. N, I	08-Oct-12			

Notes

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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